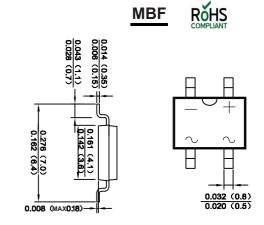


MB2F THRU MB10F

SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS

Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0



Mechanical Data

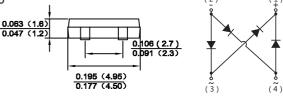
Case: JEDEC MBF Molded plastic body

Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

Polarity: Polarity symbol marking on body

Mounting Position: Any

Weight: 0.0026 ounce, 0.075 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unle ss otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	CVMPOLC	MDD	MDD	MDD	MDD	MDD	
Marking Code	SYMBOLS	MB2F	MB4F	MB6F	MB8F	MB10F	UNITS
Maximum repetitive peak reverse voltage	VRRM	200	400	600	800	1000	V
Maximum RMS voltage	VRMS	140	280	420	560	700	V
Maximum DC blocking voltage	VDC	200	400	600	800	1000	V
Maximum average forward rectified current at T _C =125°C	l _{F(AV)}			1.0			А
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	Іғѕм			35			А
Maximum instantaneous forward voltage drop per leg at 0.5A	VF			1.1			V
Maximum DC reverse current Ta=25°C at rated DC blocking voltage Ta=100°C	lR			5 0.5			uA mA
Typical junction capacitance	Cı			13			РF
Typical thermal resistance(NOTE3)	RθJA	60				°C/W	
Operating temperature range	TJ	-55 to +150					°C
storage temperature range	Тѕтс	-55 to +150				°C	

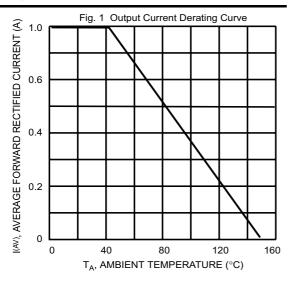
NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads

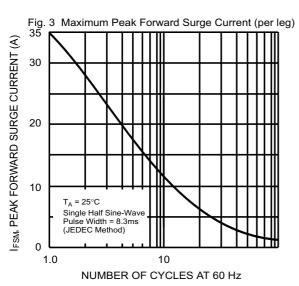
2.On aluminum substrate P.C.B. with on area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad 3.Measured at 1.0MHz and applied reverse voltage of 4.0 volts.

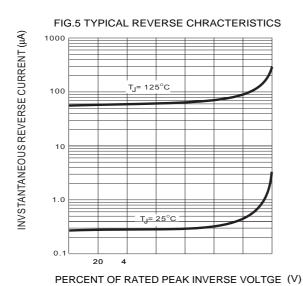
DN:T20521A0



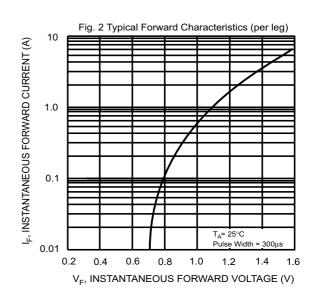
Ratings And Characteristic Curves

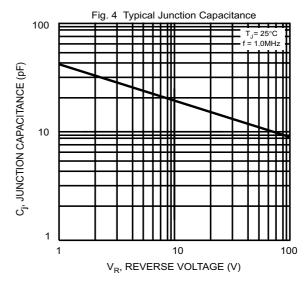




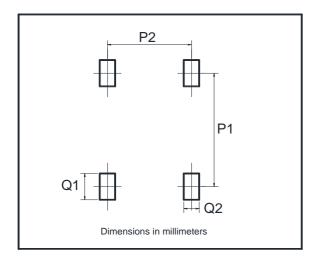


The curve above is for reference only.





Suggested Pad Layout



Dim	Min
P1	6.00
P2	2.40
Q1	1.84
Q2	1.20

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